MA4X194 (MA194)

Silicon epitaxial planar type

For switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Two isolated elements contained in one package, allowing highdensity mounting

■ Absolute Maximum Ratings $T_a = 25$ °C

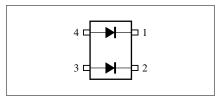
Parameter		Symbol	Rating	Unit	
Reverse voltage (DC)		V _R	40	V	
Repetitive peak reverse voltage		V _{RRM}	40	V	
Average forward current	Single	I _{F(AV)}	100	mA	
	Double	I _{F(AV)}	75	mA/Unit	
Repetitive peak forward current	Single	I_{FRM}	225	mA	
	Double	I_{FRM}	170	mA/Unit	
Non-repetitive peak forward surge current*	Single	I _{FSM}	500	mA	
	Double	I _{FSM}	375	mA/Unit	
Power dissipation		P_{D}	150	mW	
Junction temperature		T _j	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



Unit: mm 28 * 02 0.65 ± 0.15 1.5 * 0.28 0.65 ± 0.15 0.65 ± 0.15 1.5 * 0.28 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.65 ± 0.15 0.7 *

Marking Symbol: M1F

Internal Connection

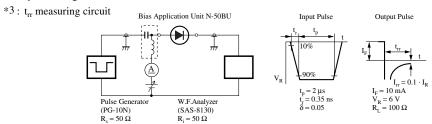


■ Electrical Characteristics $T_a = 25$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current (DC)	I_{R1}	$V_R = 40 \text{ V}$			10	nA
	I_{R2}	$V_R = 35 \text{ V}, T_a = 150^{\circ}\text{C}$			10	μΑ
Forward voltage (DC)	V _F	$I_F = 100 \text{ mA}$		0.98	1.2	V
Terminal capacitance	C _t	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$		1.0	2.0	pF
Forward dynamic resistance	$r_{\rm f}^{*1}$	$I_F = 3 \text{ mA}, f = 30 \text{ MHz}$		1.7	2.5	Ω
	$r_{\rm f}^{*2}$	$I_F = 3 \text{ mA}, f = 30 \text{ MHz}$			3.6	
Reverse recovery time*3	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			100	ns
		$I_{rr} = 0.1 \cdot I_R, R_L = 100 \ \Omega$				

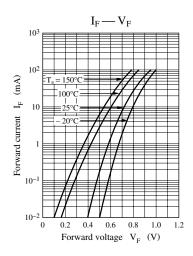
Note) *1: r_f measuring instrument: Nihon Koshuha Model TDC-121A

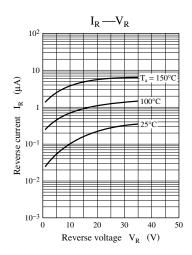
^{*2:} r_f measuring instrument: YHP 4191A RF IMPEDANCE ANALYZER

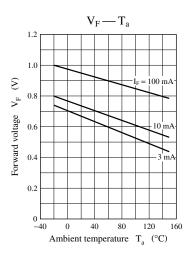


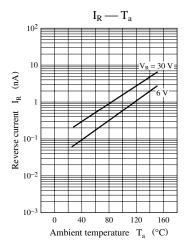
Note) The part number in the parenthesis shows conventional part number.

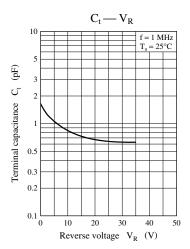
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